Specification of Thermoelectric Module TES1-13160C

Description

The 131 couples, 36.2 mm × 48.4 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

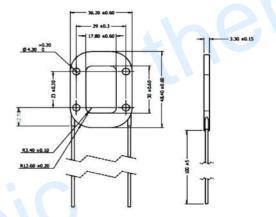
- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT (0C)	70	79	Temperature Difference between cold and hot side of the module	
DT _{max} (°C)			when cooling capacity is zero at cold side	
U _{max} (Voltage)	16.4	17.8	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	6.4	6.4	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	66.5	71.6	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	1.96	2.11	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters

Manufacturing Options A. Solder: B. Sealant:



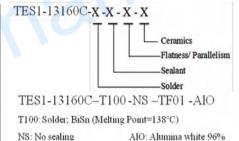
Ordering Option

Suffix	Thickness	Flatness/	Lead wire length(mm)
	H (mm)	Parallelism (mm)	Standard/Optional length
TF	$0:3.3\pm0.1$	0: 0.1/0.1	100±5/Specify
TF	1: 3.3 ± 0.05	1: 0.05/0.05	100±5/Specify

Eg. TF01: Thickness 3.3 ± 0.1 (mm) and Flatness 0.05/0.05 (mm)

- 1. T100: BiSn (Tmelt=138°C) 1. NS: No sealing (Standard)
- 2. T200: CuAgSn (Tmelt = 217°C) 2. SS: Silicone sealant
- 3. T240: SbSn (Tmelt = 240° C) 3. EPS: Epoxy sealant
- C. Ceramics: D. Ceramics Surface Options:
- 1. Alumina (Al₂O₃, white 96%) 1. Blank ceramics (not metalized)
- 2. Aluminum Nitride (AlN) 2. Metalized

Naming for the Module

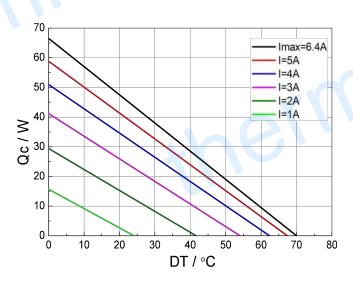


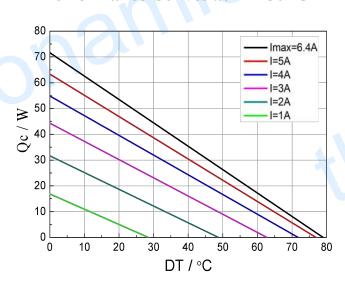
Specification of Thermoelectric Module

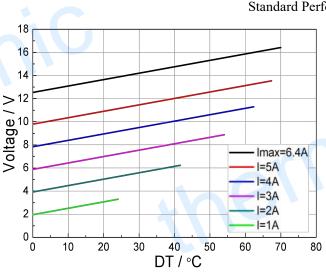
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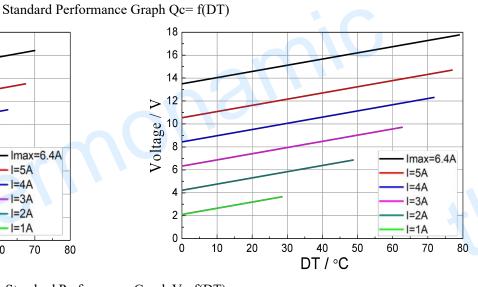
Performance Curves at Th=27 °C

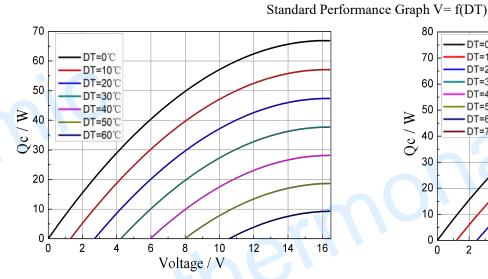
Performance Curves at Th=50 °C

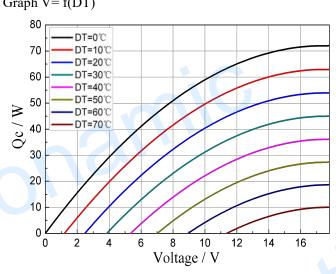










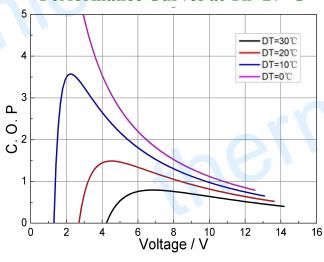


Standard Performance Graph Qc = f(V)

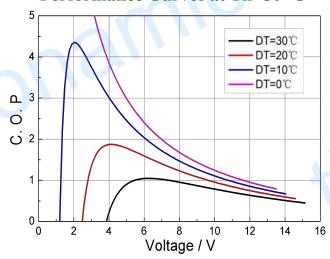
Specification of Thermoelectric Module

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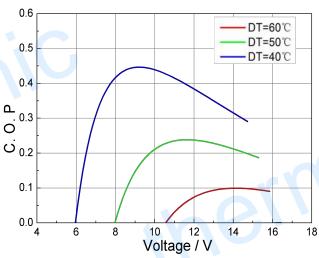


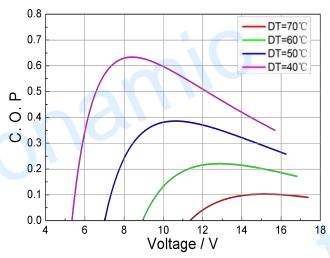


Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Operation or storage module below 100 °C
- Work under DC